



Merginamid L195/70

PRODUCT INFORMATION

Product Description

Merginamid L 195/70 is the ca. 70% solution of a polyaminoamide in xylene.

Typical Parameters

	Merginamid L 195/70
Viscosity at 25°C [mPa*s]	900 - 1 600
Amine value [mg KOH/g]	160 - 185
Colour [Gardner]	Max. 8
Solids content [%]	69 - 71
Density at 25°C [g/cm ³]	0.95
H-active-equivalent [g/Eg]	340
Use level [g/100g]	72 ¹⁾ 54 ²⁾
Gel time 250g at 23°C	Min. 12 h
Solvent	Xylene
Biobased carbon content ³⁾ [%]	56

¹⁾ Liquid epoxy resins, epoxy equivalent weight approx. 190 g/Eq

²⁾ Dispersion of a solid epoxy resin (75%), epoxy equivalent weight approx. 634 g/E

³⁾ Measure of the amount of biomass-derived carbon in a product compared to its total carbon content

Properties

Merginamid L 195/70 is phenol and nonylphenol free and does not contain benzyl alcohol. Epoxy resins cured with Merginamid L 195/70 possess the following properties:

- outstanding adhesion on metal, concrete, glass, wood, paper and plastics
- excellent flexibility and impact resistance
- low heat development and shrinkage during hardening
- exceptional dimensional stability
- very good resistance to alternating thermal stress
- high bending, compression and tensile strength
- high resistance to impact, mechanical and thermal shock
- good electrical properties such as high dielectric strength, high electrical resistance and low loss factor
- excellent resistance to water and chemicals



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Application

Merginamid L 195/70 is preferably used as hardener in lacquer resin systems and for cross linking in coating compounds at temperatures above +10 °C. In combination with liquid and solid epoxy resins Merginamid L 195/70 results in flexible and durable paintings and coatings. It is applied in corrosion protection, boat paint and adhesives.

Merginamid L 195/70 is delivered in drums and IBCs. It should be stored in moisture-proof containers around temperatures of 20 °C. Storage for longer than 12 months at favourable storage conditions does not result in reduction of utility value.

Disclaimer

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